Electronic Supplementary Material (ESI) for RSC Advances.

Supporting Information

Preparation of PGMA Chain-grafted Boron Nitride/Epoxy Composites and Their Thermal Conductivity Properties

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Figure S1. Haibao Zhang et al

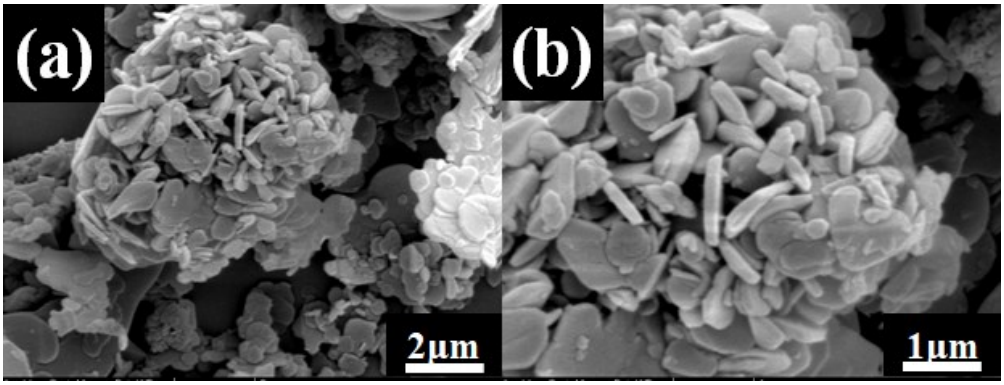

Figure S1. SEM images of the BNNS grafted by PGMA chain

Figure S2. Haibao Zhang et al

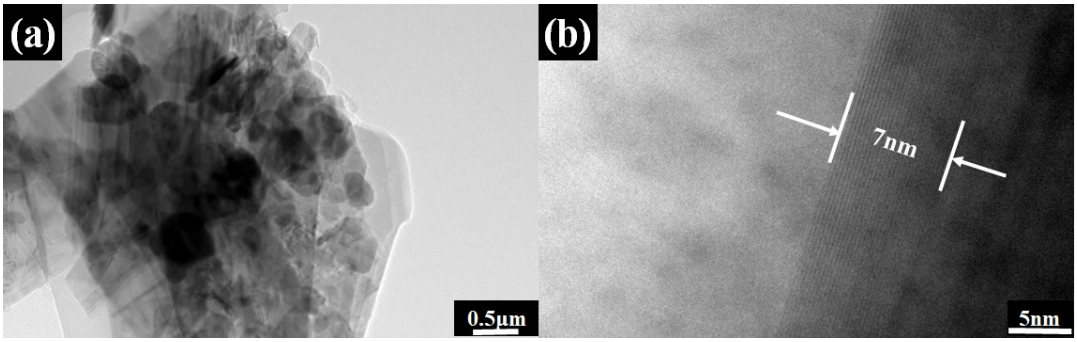

Figure S2. TEM image (a) and HRTEM image (b) of the BNNS grafted by PGMA chain, white mark is the thickness of the grafted PGMA chain

Figure S3. Haibao Zhang et al

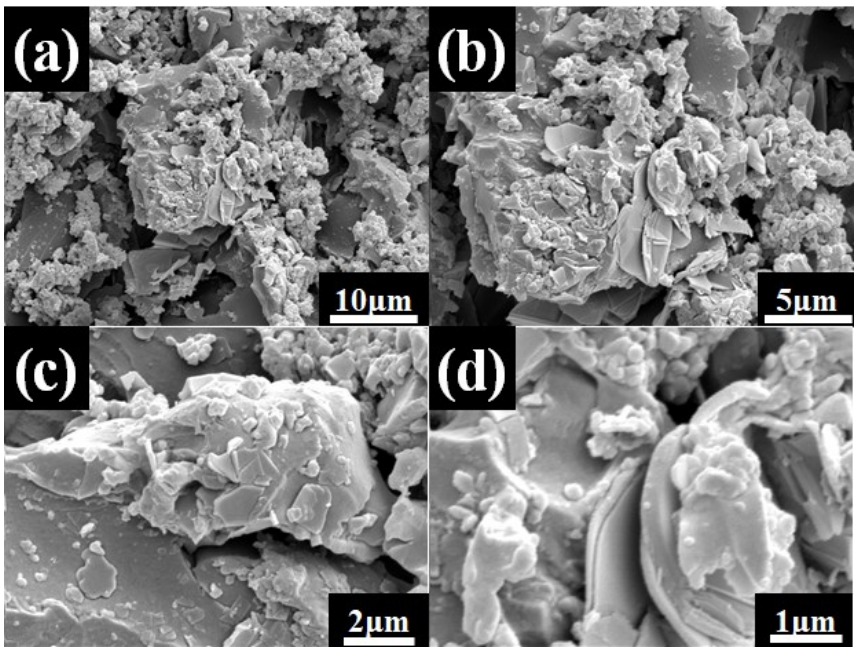

Figure S3. The SEM images of the 3 um-15um compound BNNS grafted by PGMA chain

Figure S4. Haibao Zhang et al

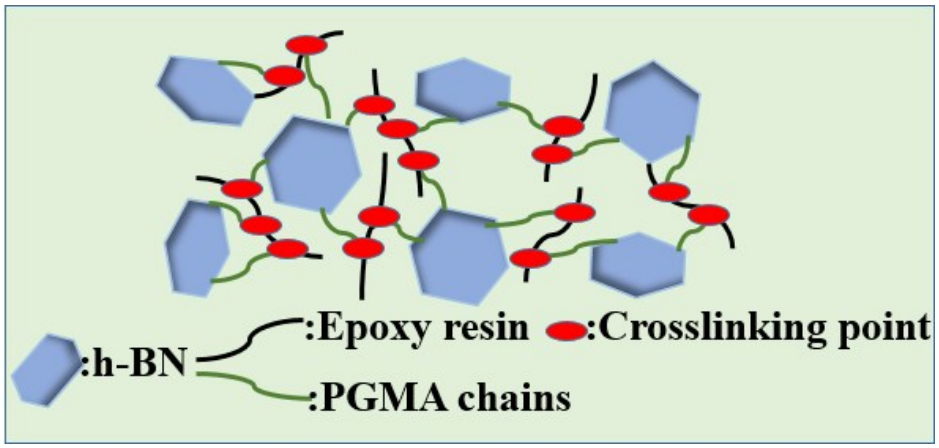

Figure S4. Bridging action of PGMA chains between h-BN and epoxy resin